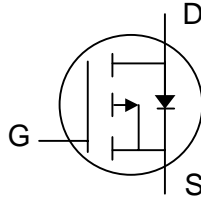




P-channel Enhancement-mode Power MOSFET

- Low On-resistance
- Simple Drive Requirement
- Fast Switching Characteristic
- RoHS-compliant, halogen-free



BV_{DSS}	-140V
$R_{DS(ON)}$	180mΩ
I_D	-15A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP15P15GH-HF-3 is in the TO-252 package, which is widely used for commercial and industrial surface-mount applications, and is well suited for low voltage applications such as DC/DC converters.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-140	V
V_{GS}	Gate-Source Voltage	±20	V
I_D at $T_C=25^{\circ}C$	Continuous Drain Current	-15	A
I_D at $T_C=100^{\circ}C$	Continuous Drain Current	-9.7	A
I_{DM}	Pulsed Drain Current ¹	-60	A
P_D at $T_C=25^{\circ}C$	Total Power Dissipation	89	W
	Linear Derating Factor	0.71	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	1.4	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient (PCB mount) ³	62.5	°C/W

Ordering Information

AP15P15GH-HF-3TR : in RoHS-compliant halogen-free TO-252, shipped on tape and reel (3000 pcs/reel)



Electrical Specifications at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-1mA$	-140	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-10V, I_D=-12A$	-	-	180	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-	-3	V
g_{fs}	Forward Transconductance	$V_{DS}=-10V, I_D=-12A$	-	12	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-120V, V_{GS}=0V$	-	-	-25	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_D=-12A$	-	55	90	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=-80V$	-	8.2	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=-10V$	-	16.6	-	nC
$t_{d(on)}$	Turn-on Delay Time ²	$V_{DS}=-50V$	-	11	-	ns
t_r	Rise Time	$I_D=-12A$	-	26	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega, V_{GS}=-10V$	-	67	-	ns
t_f	Fall Time	$R_D=4.2\Omega$	-	60	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	2850	4560	pF
C_{oss}	Output Capacitance	$V_{DS}=-25V$	-	150	-	pF
C_{riss}	Reverse Transfer Capacitance	$f=1.0MHz$	-	100	-	pF
R_g	Gate Resistance	$f=1.0MHz$	-	6.6	10	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=-12A, V_{GS}=0V$	-	-	-1.3	V
t_{rr}	Reverse Recovery Time ²	$I_S=-12A, V_{GS}=0V,$	-	75	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt=-100A/\mu s$	-	250	-	nC

Notes:

1. Pulse width limited by maximum junction temperature.
2. Pulse test - pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. Surface mounted on 1 in copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.



Typical Electrical Characteristics

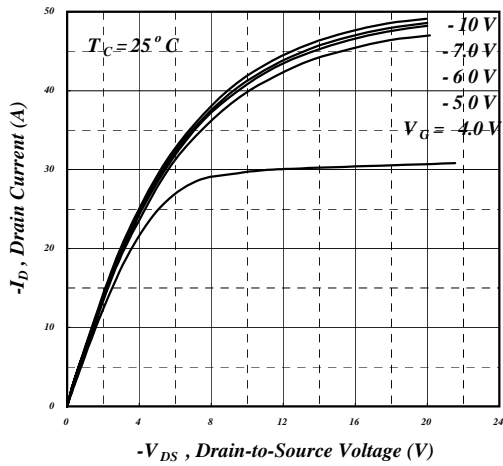


Fig 1. Typical Output Characteristics

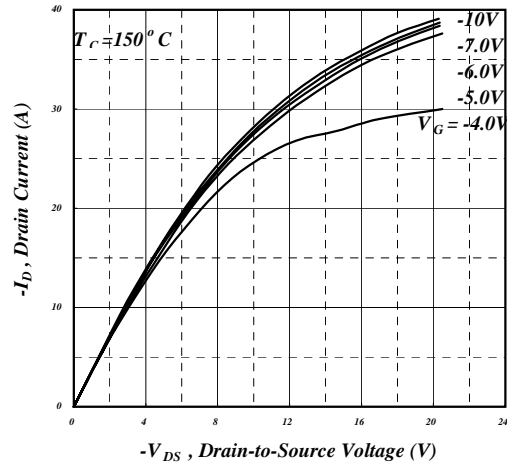


Fig 2. Typical Output Characteristics

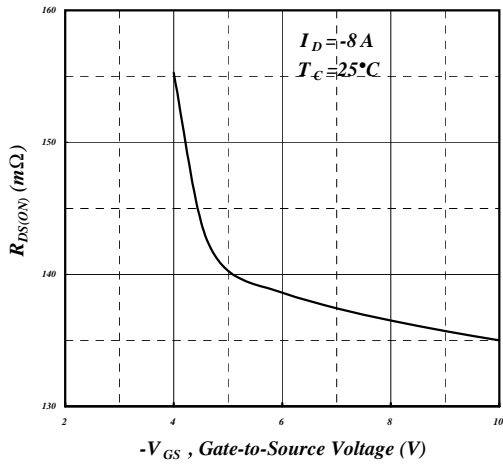


Fig 3. On-Resistance vs. Gate Voltage

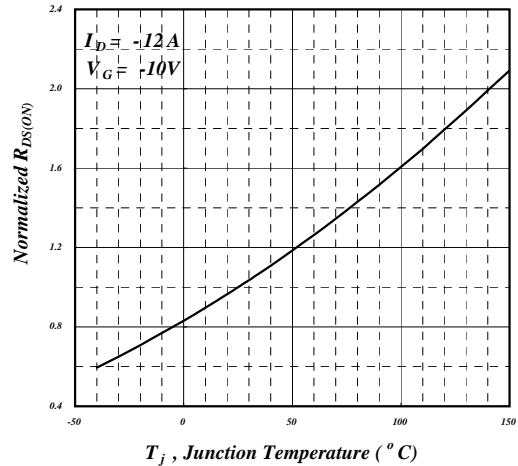


Fig 4. Normalized On-Resistance vs. Junction Temperature

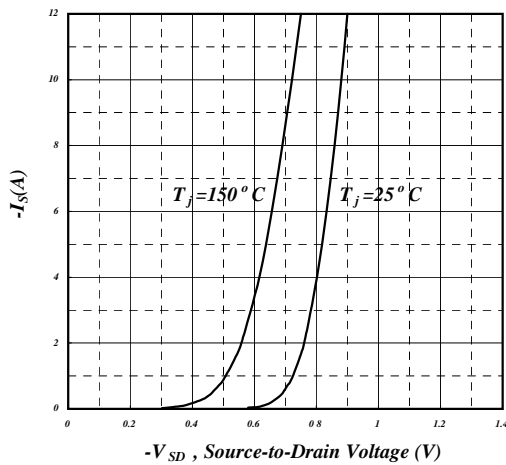


Fig 5. Forward Characteristic of Reverse Diode

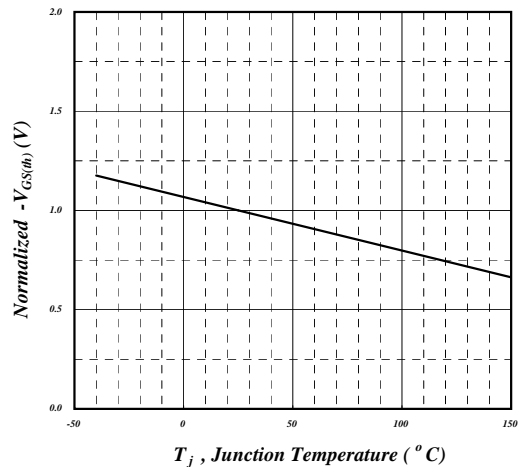


Fig 6. Gate Threshold Voltage vs. Junction Temperature



Typical Electrical Characteristics (cont.)

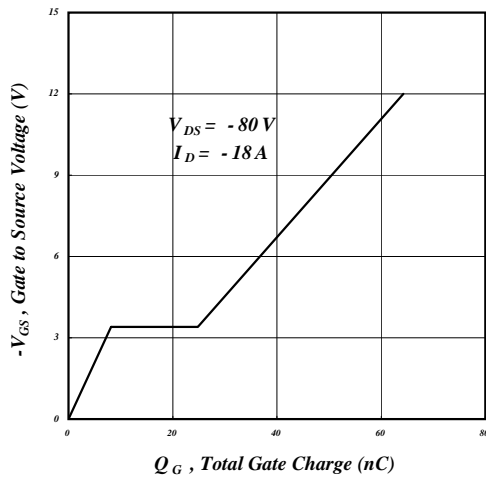


Fig 7. Gate Charge Characteristics

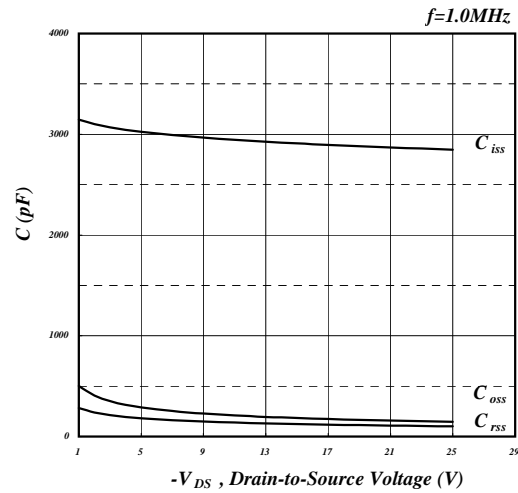


Fig 8. Typical Capacitance Characteristics

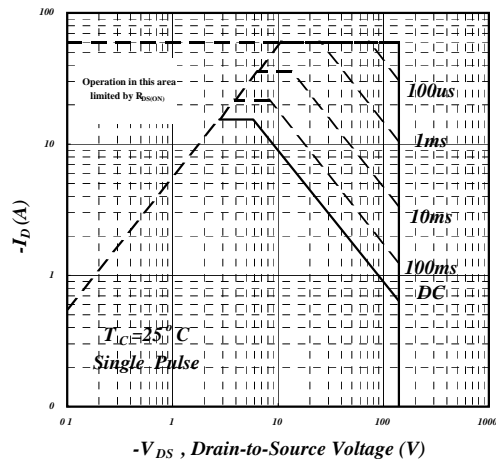


Fig 9. Maximum Safe Operating Area

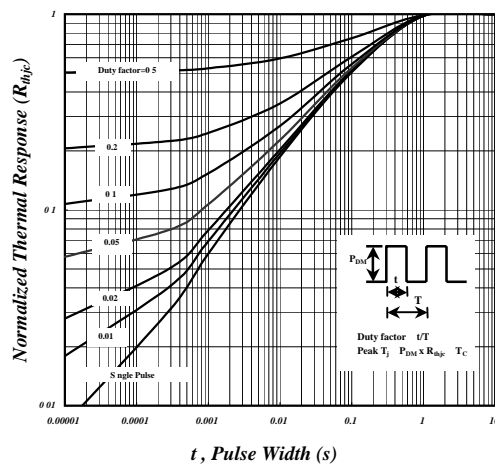


Fig 10. Effective Transient Thermal Impedance

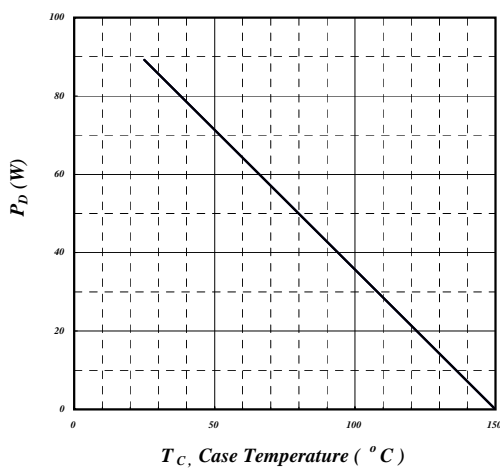


Fig 11. Typical Power Dissipation

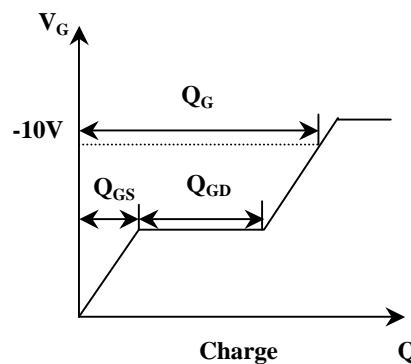
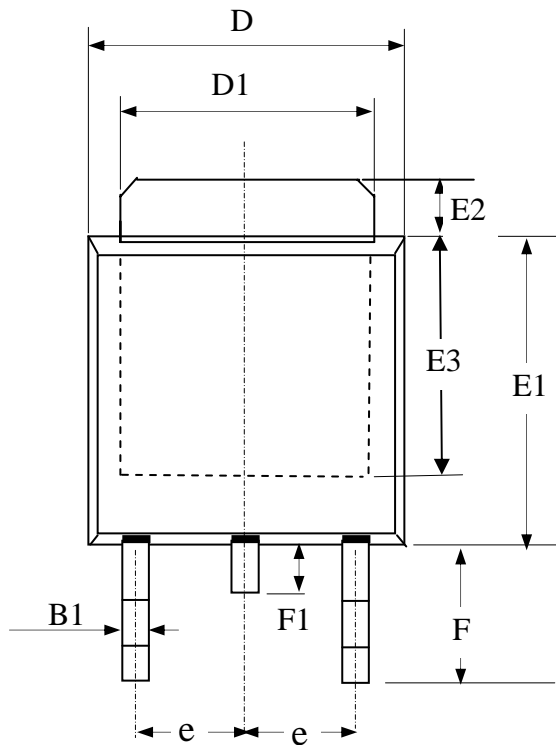


Fig 12. Gate Charge Waveform

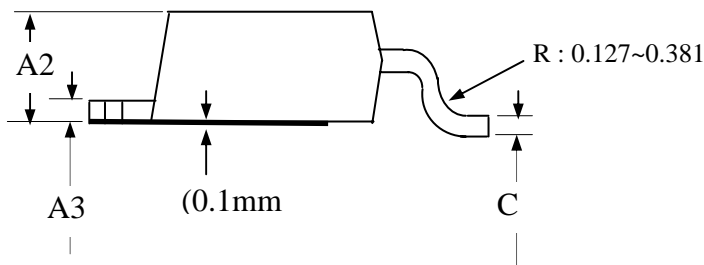


Package Dimensions: TO-252



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A2	1.80	2.30	2.80
A3	0.40	0.50	0.60
B1	0.40	0.70	1.00
D	6.00	6.50	7.00
D1	4.80	5.35	5.90
E3	3.50	4.00	4.50
F	2.20	2.63	3.05
F1	0.50	0.85	1.20
E1	5.10	5.70	6.30
E2	0.50	1.10	1.80
e	--	2.30	--
C	0.35	0.50	0.65

1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.



Marking Information

Laser Marking

